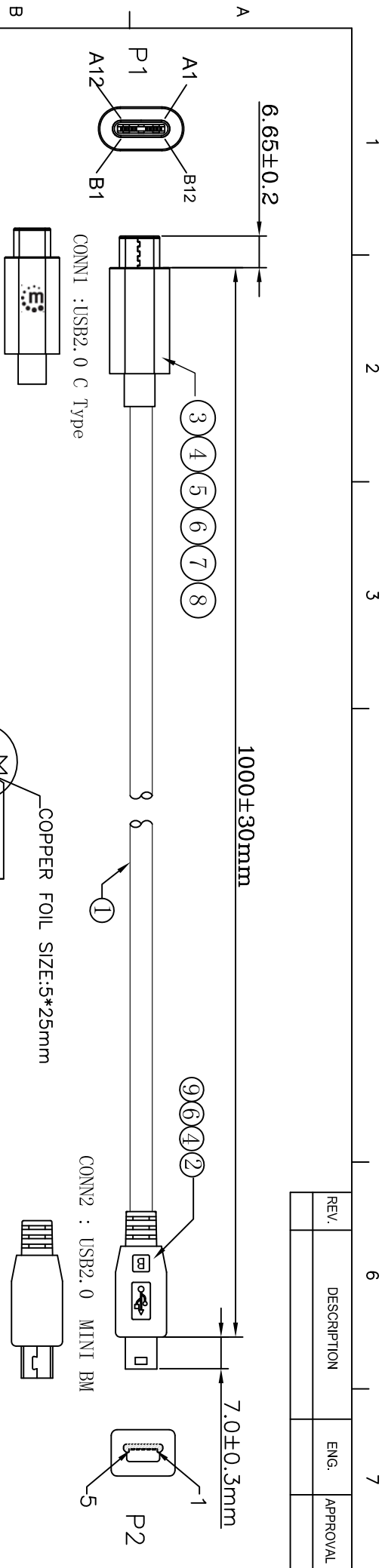
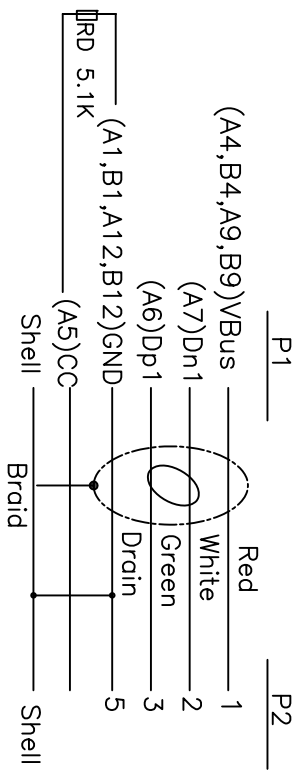


REV.	DESCRIPTION	ENG.	APPROVAL

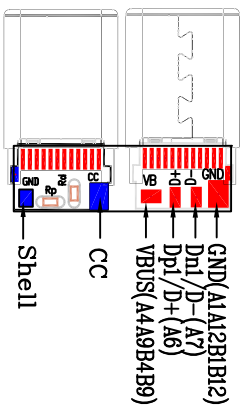


- Electrical Test:
1. 100%Test(Open ,short ,miss wire)
 2. Contact Resistance: 2 ohm max.
 3. Insulation Resistance: 100M ohm Min.
 4. Hi-Pot: 300VDC/10ms.

Pin Assignment



TYPE-C PCB pictorial view:



NO	DESCRIPTION	QTY	UNIT
①	NO-UL30AWG(19/0.061C)*2C+24AWG(26/0.1TC+250Dn)/en)+3E(19/0.05TC+250Dn)/en)	1.0	m
②	++AB(16/9/0.06TC 95S) 0D:3.0MM Color:BLACK no mark	1.0	m
③	INS2.0 MINI BM SOLDER INSULATION:BLACK SHELL NICKEL PLATED	1	Set
④	Inside Molding: PE	4	g
⑤	USB 3.1 C Type Connector Back Insulation Nickel Plated Shell With PCB(Resistance:5.1K)	1	pcs
⑥	H.S.T Ø1.0 BLACK	0.016	M
⑦	USB TYPE C~n Front Nickel Plated Shell~(OD2.7~3.2MM)	1	pcs
⑧	USB TYPE C~n Back Nickel Plated Shell~(OD2.7~3.2MM)	1	pcs
⑨	Copper Foil:W=5MM 25u	0.025	M

TOLERANCE(INCH)	TOLERANCE(MM)
X ±0.02"	X ±0.5mm
X.X ±0.01"	X.X ±0.20mm
X.XX ±0.008"	X.XX ±0.15mm
X.XXX ±0.005"	X.XXX ±0.10mm

TITLE: MH USB 3.1 Cbl CM-MINI BM,Black,3R/1m		APPD	Date
CUSTOMER: 353328	Check		16.03.03
ICT P/N:	Unit	mm	Projection
DWG.NO:	Scale	1:1	Size: A4
	Sheet	1 of	REV. d

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